



## PATENT ABSTRACTS OF JAPAN

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**H05K 3/46**(21) Application number: **08316445**(22) Date of filing: **27.11.96**(71) Applicant: **KYOCERA CORP**(72) Inventor: **WAKASAKI AKIRA****(54) MULTILAYER WIRING BOARD****(57) Abstract:**

**PROBLEM TO BE SOLVED:** To provide a multilayer wiring board having wiring conductors all or some of which are formed by the thin film forming technique to provide a high density of the wiring conductors.

**SOLUTION:** The multilayer wiring board has a substrate 1, org. resin insulation layers 3a, 3b, 3c, 3d deposited on a board 1 and a power source thin film wiring conductor layer 4a, a grounding thin film wiring conductor layer 4b and signal thin film wiring conductor layers 4c, 4d disposed among the insulation layers 3a, 3b, 3c, 3d. The power source thin film wiring conductor layer 4a and the grounding thin film wiring conductor layer 4b have openings H arranged each like a meshed grid and the conductors of the layer 4a face the openings H of the layer 4b while the conductors of the layer 4b face the openings H of the layer 4a.

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